

REMARKS

Claims 34-40, 45-62, 82 and 83 are pending. By this Amendment, claim 48 is amended and claim 83 is added.

Claims 48-51 were rejected under 35 U.S.C. §112, second paragraph. By this Amendment, claim 48 has been amended as suggested by the Examiner in order to clarify that the coating is an additional coating. It is respectfully requested that the rejection be withdrawn.

Claims 34-40, 45-46, 52-54, 58, 59 and 82 were rejected under 35 U.S.C. §103(a) over Hasabe et al. (Hasabe), U.S. Patent No. 5,658,615. This rejection is respectfully traversed.

Hasabe fails to disclose or suggest a method of applying a coating, comprising the steps of spreading the coating by causing the article to revolve and applying the coating directly to a surface of the article which is not covered by the predetermined quantity of coating spreading under the effect of centrifugal force as recited in claim 34.

As admitted on page 4 of the Office Action, Hasabe fails to specifically disclose applying a solvent directly to a surface of the article which is not covered by the coating spreading under the effect of centrifugal force. The Examiner then asserts that it would have been obvious to disclose such a feature. Applicant respectfully traverses this assertion.

Hasabe discloses a method for forming a coating film on a semiconductor wafer. The embodiment of Fig. 14 discloses a solvent supply nozzle 3 branched into a plurality of portions (i.e., nozzles 3a) such that the solvent is supplied to the four portions at the same time (col. 11, line 56 - col. 12, line 5). However, as with the other embodiments, the solvent is diffused by rotating the substrate. In other words, the solvent is only diffused on the substrate using centrifugal force and not in two different manners (i.e. centrifugal force and direct application).

As shown in Fig. 14 of Hasabe, the nozzles 3a are configured for dropping solvent at positions marked "A" at a predetermined distance from the corners of the substrate G.

Hasabe specifically places the nozzles 3a at a predetermined distance from the corners of the substrate so that the solvent can be uniformly diffused using centrifugal force. As such, Hasabe discloses the opposite of Applicant's application of a solvent directly to a surface of the article which is not covered by the coating spreading under the effect of centrifugal force. Hasabe thus fails to disclose or suggest Applicant's claim 34, and to the contrary teaches away from it.

In addition, claims 35-40, 45, 46, 52-54, 58, 59 and 82 recite additional features of the invention and are also believed to be allowable at least for the reasons discussed above with respect to claim 34 and for the additional features recited therein. It is respectfully requested that the rejection be withdrawn.

Claims 34-40, 46, 47, 52-54 and 57-62 were rejected under 35 U.S.C. §103(a) over Iwasaki, U.S. Patent No. 5,002,799 (Iwasaki '799) in view of Hasabe. The rejection is respectfully traversed.

Iwasaki '799 discloses a method of manufacturing anti-static cathode ray tubes wherein the coating is deposited on a surface of the face plate 104 from an injection nozzle 116 (Fig. 8). However, Iwasaki '799 fails to disclose or suggest a method of applying a coating which includes both the spreading of the coating by causing the article to revolve and the applying of the coating directly to a surface of the article which is not covered by the predetermined quantity of coating under the effect of centrifugal force as recited in claim 34. As discussed above, Hasabe also fails to disclose or suggest this feature and thus fails to overcome the deficiencies of Iwasaki '799.

In addition, claims 35-40, 46, 47, 52-54 and 57-62 recite additional features of the invention and are also believed to be allowable at least for the reasons discussed above with

respect to claim 34 and for the additional features recited therein. It is respectfully requested that the rejection be withdrawn.

Claims 55 and 56 were rejected under 35 U.S.C. §103(a) over Iwasaki '799 in view of Hasabe as applied to claim 34, and further in view of Iwasaki, U.S. Patent No. 5,599,579 (Iwasaki '579). The rejection is respectfully traversed.

None of the applied references disclose or suggest the features recited in claim 34. In addition, claims 55 and 56 recite additional features of the invention and are also believed to be allowable at least for the reasons discussed above with respect to claim 34, and for the additional features recited therein. It is respectfully requested that the rejection be withdrawn.

Applicant appreciates the Examiner's indication of allowability for claims 48-51. However, for the reasons discussed above, Applicant asserts that all of claims 34-40, 45-62, 82 and 83 are allowable.

In view of the foregoing amendments and remarks, Applicant submits that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number set forth below.

Respectfully submitted,



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